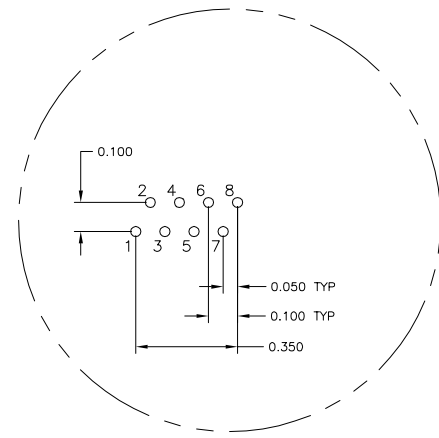
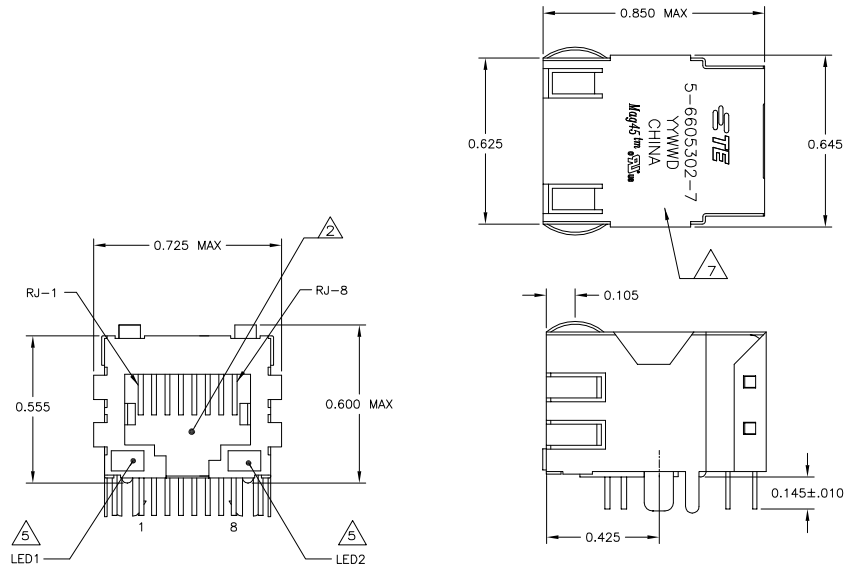


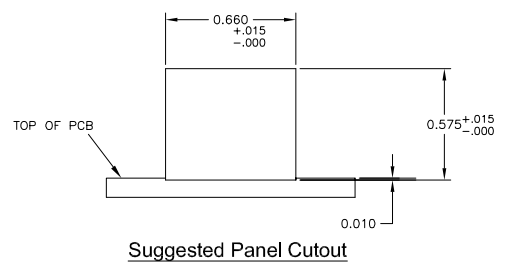
LOC		REV		REVISIONS			
AA	22	#	DATE	DESCRIPTION	DATE	BY	APP
		B1	25MAR11	REVISED PER ECO-11-005140		RK	HMR
		C	30MAY2011	ECO-11-015766		EL	LR

MECHANICAL:

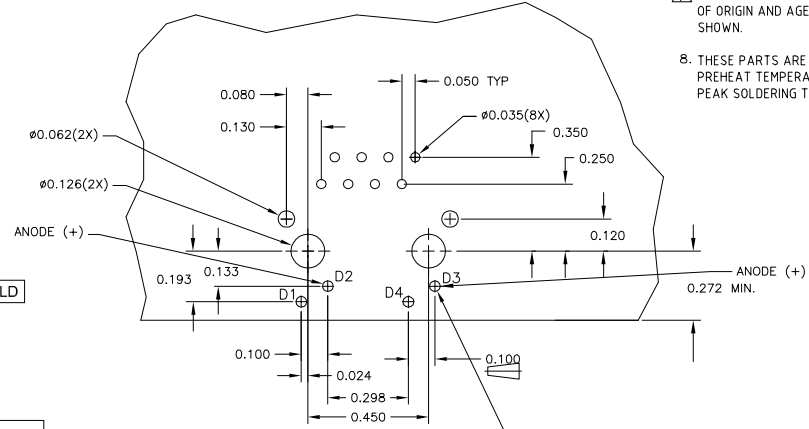
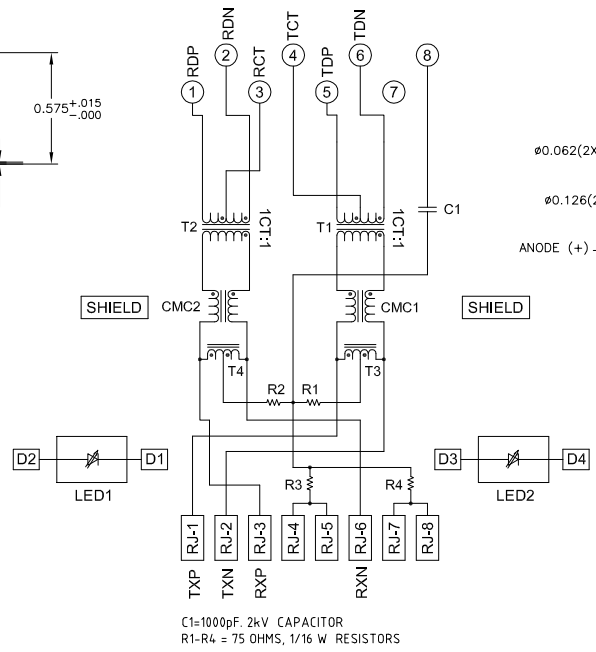


Pin Designations

- NOTES:**
- △ MATERIALS: HOUSING - THERMOPLASTIC PET POLYESTER FLAMMABILITY RATING UL 94V-0. SHIELD - .010" THICK, C26800 BRASS PREPLATED WITH 30µINCH SEMI-BRIGHT NICKEL. SOLDER TABS POST DIPPED WITH 100µINCH MIN SAC SOLDER. MOD JACK CONTACTS - 0.0157 X 0.018" PHOSPHOR BRONZE, 50µINCH MIN OVERALL NICKEL UNDERPLATE, WITH SELECT 50µINCH MIN HARD GOLD FINISH PLATE SOLDER TAILS WITH 100µINCH MIN MATTE TIN AND/OR SAC SOLDER DIP. LIGHT EMITTING DIODE(LED) - DIFFUSED EPOXY LENS, .020" x .020" CARBON STEEL WIREFRAME LEADS PRE-PLATED WITH 80µINCH SILVER OVER 40µINCH NICKEL UNDERPLATE OVER 40µINCH COPPER UNDERPLATE. POST-PLATED WITH 100µINCH MIN MATTE TIN AND/OR SAC SOLDER DIP OR PURE TIN SOLDER DIP.
 - △ RJ45 JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUB PART F.
 - △ MAGNETICS
-IMPEDANCE: 100 OHMS
-TURNS RATIO (CHIP-CABLE): TX = 1:1, RX = 1:1
-OPEN CIRCUIT INDUCTANCE (OCL): 350µH MIN @100kHz, 0.1VRMS, 8mADC BIAS FROM 0°C TO 70°C, TX AND RX
-PERFORMANCE @ 25°C:
 INSERTION LOSS (IL): 11dB MAX FROM 0.5MHz TO 100MHz
 RETURN LOSS (RL): 18dB MIN FROM 0.5MHz TO 30MHz
 18-20LOG(f/30)dB MIN FROM 30.1MHz TO 60MHz
 12dB MIN FROM 60.1MHz TO 80MHz
 CROSSTALK ATTENUATION: 35dB MIN FROM 0.5MHz TO 40MHz
 33-20*LOG(f/50)dB MIN FROM 40.1MHz TO 100MHz
 COMMON MODE REJECTION RATIO (CMRR): 30dB MIN FROM 0.5MHz TO 100MHz
 -ISOLATION VOLTAGE: 2250VDC (MAX) FOR 60 SECONDS WITH A RISE TIME OF 500V/SEC.
 - 4. OPERATING TEMPERATURE: FROM 0°C - +70°C
 - △ LEDs ARE DRIVEN WITH CONSTANT CURRENT AT APPROX 20mA.
LED COLOR: DOMINANT WAVELENGTH (λD): GREEN 568 nm TYP @ IF=20mA
FORWARD VOLTAGE (VF): GREEN 2.2V TYP @ IF=20mA
DOMINANT WAVELENGTH (λD): YELLOW 588 nm TYP @ IF=20mA
FORWARD VOLTAGE (VF): YELLOW 2.1V TYP @ IF=20mA.
 - △ INDICATED CONNECTIONS ARE FOR NIC CONFIGURATION. THE MAGNETICS ARE SYMMETRICAL, AND SUPPORT AUTO-MDI/MDIX.
 - △ TE CONNECTIVITY LOGO, TE CONNECTIVITY PART NUMBER, DATE CODE, COUNTRY OF ORIGIN AND AGENCY APPROVAL MARKING IN APPROXIMATE LOCATION SHOWN.
 - 8. THESE PARTS ARE RECOMMENDED FOR WAVE SOLDERING PROCESS, PREHEAT TEMPERATURE IS 120°C TO 160°C, 120 SECONDS TO 180 SECONDS, PEAK SOLDERING TEMPERATURE IS 260 °C MAX, 10 SECONDS MAX.



315 SERIES MAGNETIC CIRCUIT



Suggested PCB Layout (Component Side)

YES	GREEN	YELLOW	5-6605302-8
YES	GREEN	GREEN	5-6605302-7
2KV DECOUPLING CAPACITOR		LED1	LED2
		PART NUMBER	

THIS DRAWING IS A CONTROLLED DOCUMENT.		SHEET 1 OF 1	
DRAWING NO: 108-2100		SCALE: NTS	
CUSTOMER DRAWING		REV C	